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Flexible From -55 to 150°C

"Phase-Change" Dry Pad

High Melt-flow >135°C

Bond with Placement Pressure

>1000 V Insulation @ 3 mil

IDEAL FOR:

- Thermal Grease Replacement
- Thermal Gasket Replacement
- Thermal Adhesive Interface
- BGA Die Heatspreader Interface

DESCRIPTION:

CP7138-2KP is an aluminum nitride crystallite filled, electrically insulating, medium bond strength thermal interface material protected with polyimide sheet. It is designed to enhance thermal transfer from power device to heat-sink. CP7138-2KP has CP7138 sandwiching a 2-mil polyimide high dielectric strength carrier and is dry and handles well with automated excise-placement equipment and forms a good bond with placement pressure similar to paste adhesives.

UL 94V-O / UL 746A Rated

AVAILABILITY:

CP7138-2KP is available in sheet sizes, reel, and as custom preforms. Standard thicknesses are 0.006" and 0.0012". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Cut or pre-cut to desired size and shape.
- (2) Place COOL-PAD between device and heatspreader or heat-sink.
- (3) If it is pre-applied onto heatsink, heatspreader or CPU, micromesh protected surface should face out.
- (4) Place onto parts that are heated above 135°C using nominal placement pressure

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

COOL-PAD
CP7138-2KP

TYPICAL PROPERTIES*

Electrical Resistivity	>1x10 ¹⁴ ohm-cm
(25 °C/ As is)	
Dielectric Strength (Volts/mil)	>3000
Glass Transition Temp.(°C)	-55 ±10%
Lap-Shear Strength	<>600 psi
	<>4.1 N/mm ²
Device Push-off Strength	<>800 psi
	<5.5 N/mm ²
Hardness (Type)	<60 (A)
Cured Density (gm/cc)	2.5 ±10%
Thermal Conductivity	>28 Btu-in/hr-ft ² -°F
	>4.0 W/m-°C
Linear Thermal Expansion	110 ±15%
Coeff. (ppm/°C)	
Maximum Continuous Operation Temp. (°C)	<150

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Melt/Flow Conditions

Temperature	Time	Pressure
>135°C	0.5sec	Nominal

SHELF LIFE:

Storage temperature	Shelf Life
25°C	1 yr